

B3 --A laser is irradiated against the upper surface 42 of the solder resist 4 to remove the solder resist 4 along the conductor patterns 3, as shown in Fig. 4(C). Laser irradiation is stopped when 5% of the height p of the conductor pattern 3 is exposed. This exposes the upper portion 32 of the conductor pattern 3, or the top surface 320 and the side surfaces 325 to openings 40 of the solder resist 4. In this state, the height h of the lower portion 31 of the conductor pattern 3 is 95% of the height p of the conductor pattern 3.--

In the Claims:

In accordance with 37 C.F.R. § 1.121(c)(1)(i), the following is a clean version of the amended claims. A marked-up version of the amended claims in accordance with 37 C.F.R. § 1.121(c)(1)(ii) is enclosed herewith. Claims 1, 2, 4, 7 and 8 are amended in this amendment.

- B4
1. (Amended) A printed circuit board comprising:
- an insulative substrate;
 - a conductor pattern formed on the substrate; and
 - a protection film coating the substrate and the conductor pattern, wherein the conductor pattern includes a bottom surface contacting the substrate, a top surface opposite to the bottom surface, and a pair of side surfaces, each of the side surfaces having a lower side surface covered by the protection film and an upper side surface exposed from the protection film, wherein both the bottom surface and the top surface have widths, both the lower side surface covered by the protection film and the conductor pattern have heights, and wherein the width of the bottom surface is greater than the width of the top surface.

cont.
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2. (Amended) The printed circuit board according to claim 1, wherein the conductor pattern has a trapezoidal cross-section that is perpendicular to the bottom surface of the conductor pattern.

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4. (Amended) The printed circuit board according to claim 1, wherein the height of the lower side surface covered by the protection film in the conductor pattern is 50% or greater and less than 100% of the height of the conductor pattern.

7. (Amended) The printed circuit board according to claim 1, wherein a value X is obtained by the following formula:

$$X = ((c-d)/2)/p$$

where c is the width of the bottom surface, d is the width of the top surface, and p is the height of the conductor pattern, and wherein X is in the range of 0.1 to 2.5.

B6/c2

8. (Amended) A method for fabricating a printed circuit board comprising the steps of:
etching an insulative substrate including a conductor to form a conductor pattern, wherein the conductor pattern is formed so that a width of a bottom surface contacting the substrate is greater than a width of a top surface, which is opposite the bottom surface;
applying an insulative protection film to the conductor pattern and the substrate; and
removing part of the protection film to expose an upper portion of the conductor pattern.

REMARKS

This is in response to the Office Action mailed November 21, 2001. The specification and claims have been amended to correct certain informalities pointed out by the Examiner. Support for those amendments is given in the following sections.